



Material Content Data Sheet



Sales Product Name		IPG20N06S2L-50		Issued		19. January 2018		
MA#		MA000685674						
Package		PG-TDSON-8-4		Weight*		96.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.328	2.40	2.40	24049	24049
leadframe	non noble metal	iron	7439-89-6	0.045	0.05		462	
	inorganic material	phosphorus	7723-14-0	0.013	0.01		139	
	non noble metal	copper	7440-50-8	44.654	46.13	46.19	461334	461938
wire	non noble metal	aluminium	7429-90-5	0.760	0.79	0.79	7854	7854
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		928	
	plastics	epoxy resin	-	6.375	6.59		65861	
	inorganic material	silicondioxide	60676-86-0	38.429	39.70	46.38	397021	463810
leadfinish	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13510	13510
plating	non noble metal	nickel	7440-02-0	0.048	0.05		496	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.05	1	497
solder	noble metal	silver	7440-22-4	0.069	0.07		709	
	non noble metal	tin	7440-31-5	0.055	0.06		567	
	non noble metal	lead	7439-92-1	2.620	2.71	2.84	27066	28342
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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